CLAIMS

[Claim 1]

A resin composition comprising:

a thermosetting resin (A); and

a thermoplastic resin (B), wherein

the thermoplastic resin (B) contains a block copolymer (B1) including a block (b1) that contains a structural unit derived from an aromatic hydrocarbon compound, and a block (b2) that contains a structural unit derived from a conjugated diene compound,

the component (B1) does not contain a diblock copolymer, or when the component (B1) contains a diblock copolymer, the content of the diblock copolymer is 50% by mass or less in the component (B1), and

the weight-average molecular weight of the component (B1) is 130,000 or less.

[Claim 2]

The resin composition according to Claim 1, wherein

the conjugated diene compound is one or more selected from the group consisting of butadiene and isoprene.

[Claim 3]

The resin composition according to Claim 1 or 2, wherein

in the (B1) component, the block (b2) further contains a structural unit derived from an aromatic hydrocarbon compound, and in the block (b2), a content ratio of the structural unit derived from the conjugated diene compound to the structural unit derived from the aromatic hydrocarbon compound [structural unit derived from conjugated diene compound/structural unit derived from aromatic hydrocarbon compound] is 99/1 to 50/50.

[Claim 4]

The resin composition according to any one of Claims 1 to 3, wherein

the thermosetting resin (A) contains one or more selected from the group consisting of an epoxy resin, a maleimide compound, a modified polyphenylene ether resin, a phenolic resin, a polyimide resin, a cyanate resin, an isocyanate resin, a benzoxazine resin, an oxetane resin, an amino resin, an unsaturated polyester resin, an allyl resin, a dicyclopentadiene resin, a silicone resin, a triazine resin, and a melamine resin.

[Claim 5]

The resin composition according to Claim 4, wherein

the maleimide compound contains one or more selected from the group consisting of a maleimide compound having one or more N-substituted maleimide groups and a derivative of the maleimide compound.

[Claim 6]

The resin composition according to Claim 5, wherein

the maleimide compound contains one or more selected from the group consisting of an aromatic bismaleimide compound having two N-substituted maleimide groups bonded to an aromatic ring and an aromatic polymaleimide compound having three or more N-substituted maleimide groups bonded to an aromatic ring.

[Claim 7]

The resin composition according to Claim 6, wherein

the aromatic bismaleimide compound having two N-substituted maleimide groups bonded to an aromatic ring contains an indane ring-containing aromatic bismaleimide, and the aromatic polymaleimide compound having three or more N-substituted maleimide groups bonded to an aromatic ring contains a biphenyl aralkyl maleimide.

[Claim 8]

The resin composition according to any one of Claims 1 to 7, further comprising:

an inorganic filler (C).

[Claim 9]

The resin composition according to any one of Claims 1 to 8, further comprising:

(D) one or more selected from the group consisting of a conjugated diene polymer and a modified conjugated diene polymer.

[Claim 10]

A prepreg comprising:

the resin composition according to any one of Claims 1 to 9 or a semi-cured product of the resin composition.

[Claim 11]

A resin film comprising:

the resin composition according to any one of Claims 1 to 9 or a semi-cured product of the resin composition.

[Claim 12]

A laminate comprising:

a cured product of the resin composition according to any one of Claims 1 to 9 or a cured product of the prepreg according to Claim 10; and

a metal foil.

[Claim 13]

A printed wiring board comprising:

a cured product of the resin composition according to any one of Claims 1 to 9.

[Claim 14]

A semiconductor package comprising:

the printed wiring board according to Claim 13; and

a semiconductor element.